

Report NO.: MG00001000168

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJP50P06S
Package Type :	TO-220-3L-C

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.2915%
Lead Frame	Iron	7439-89-6	0.06%	14.9829%
	Phosphorus	7723-14-0	0.04%	
	Copper	7440-50-8	99.90%	
	Silver	7440-22-4	0.01%	
	Al	7429-90-5	99.99%	
Wire1	others	/	0.01%	0.0358%
	copper	7440-50-8	99.99%	
Wire2	others	/	0.01%	0.0885%
	Lead	7439-92-1	92.50%	
Epoxy	Tin	7440-31-5	5.00%	0.6745%
	Silver	7440-22-4	2.50%	
	Silica	60676-86-0	79.40%	
Mold Compound	Epoxy Resin	29690-82-2	8.62%	83.5425%
	Phenol Resin	Trade secret	6.89%	
	Fire Retardant	Trade secret	4.65%	
	Carbon black	1333-86-4	0.44%	
Plating	Tin	7440-31-5	100.00%	0.3843%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.